

Title (en)

METHOD FOR APPLYING AN ELECTRICAL MICROSTRUCTURE, ELASTOMER STRUCTURE, FIBER COMPOSITE COMPONENT, AND TIRE

Title (de)

VERFAHREN ZUR ANBRINGUNG EINER ELEKTRISCHEN MIKROSTRUKTUR SOWIE ELASTOMERSTRUKTUR, FASERVERBUNDBAUTEIL UND REIFEN

Title (fr)

PROCÉDÉ DE DÉPÔT D'UNE MICROSTRUCTURE ÉLECTRIQUE AINSI QUE STRUCTURE ÉLASTOMÈRE, ÉLÉMENT COMPOSÉ DE FIBRES ET PNEU

Publication

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Application

EP 17805160 A 20171121

Priority

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Abstract (en)

[origin: WO2018104047A1] The invention relates to a method for applying an electrical microstructure on or in an object of any type, wherein the electrical microstructure is first applied to a flexible film and the film is fastened, with the electrical microstructure applied thereto in front, to a fastening surface of the object by adhesive bonding and/or vulcanization attachment. The invention further relates to an elastomer structure, to a fiber composite component, and to a motor-vehicle tire, each having at least one electrical microstructure fastened thereto by adhesive bonding and/or vulcanization attachment.

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Citation (search report)

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